

U.S. PTO
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FOR (Rev.)

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U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

FORMATION FORM COVER SHEET
PATENTS ONLY

Attorney Docket No.: 48370-0029

To the Commissioner for Patents

ATTN: MAIL STOP ASSIGNMENT RECORDATION SERVICES

Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

- 1) Akinori SHIRAISHI
- 2) Yuichi TAGUCHI
- 3) Masahiro SUNOHARA
- 4) Hideaki SAKAGUCHI
- 5) Naoyuki KOIZUMI
- 6) Kei MURAYAMA
- 7) Mitsutoshi HIGASHI

Additional names of conveying party(ies) attached?

Yes No

2. Name and address of receiving party(ies):

Name: SHINKO ELECTRIC INDUSTRIES CO., LTD.

Address: 80, Oshimada-machi, Nagano-shi,
Nagano, 381-2287, Japan

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3. Nature of conveyance:

- Assignment
- Security Agreement
- Other _____
- Merger
- Change of Name

Execution Date: (1-7) January 26, 2007

Additional name(s) & address(es) attached?

Yes No

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4. New Application number(s) or patent number(s): **NEW APPLICATION**

If this document is being filed together with a new application the execution date of the application is:

(1-7) January 26, 2007

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached: Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: John G. Smith

Internal Address: DRINKER BIDDLE & REATH LLP
Customer No. 55694

Street Address: 1500 K. Street, NW., Suite 1100
City: Washington State: D.C. Zip: 20005-1209

6. Total number of applications and patents involved: 1

7. Total fee (37 C.F.R. §3.41): \$40.00

- Enclosed
- Authorized to be charged to Deposit Account 50-0573

8. Deposit Account No. 50-0573
(Attach duplicate page if paying by deposit account)

9. Statement and Signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

John G. Smith, Reg. No. 33,818

Name of Person Signing

Signature

February 1, 2007

Date

Total number of pages including cover sheet, attachments and documents: 3

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ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on _____, (Serial No. _____); and

WHEREAS, Shinko Electric Industries Co., Ltd., a corporation of Japan, whose post office address is 80, Oshimada-machi, Nagano-shi, Nagano, 381-2287, Japan, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. _____, filed _____) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of Sole or First Assignor Akinori SHIRAISHI	Assignor's Signature <i>Akinori Shiraishi</i>	Date January 26, 2007
Address c/o Shinko Electric Industries Co., Ltd., 80, Oshimada-machi, Nagano-shi, Nagano, 381-2287, Japan		Citizenship Japan
Full Name of Second Assignor Yuichi TAGUCHI	Assignor's Signature <i>Yuichi Taguchi</i>	Date January 26, 2007
Address c/o Shinko Electric Industries Co., Ltd., 80, Oshimada-machi, Nagano-shi, Nagano, 381-2287, Japan		Citizenship Japan
Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

Full Name of Third Assignor Masahiro SUNOHARA	Assignor's Signature <i>Masahiro Sunohara</i>	Date January 26, 2007
Address c/o Shinko Electric Industries Co., Ltd., 80, Oshimada-machi, Nagano-shi, Nagano, 381-2287, Japan		Citizenship Japan
Full Name of Fourth Assignor Hideaki SAKAGUCHI	Assignor's Signature <i>Hideaki Sakaguchi</i>	Date January 26, 2007
Address c/o Shinko Electric Industries Co., Ltd., 80, Oshimada-machi, Nagano-shi, Nagano, 381-2287, Japan		Citizenship Japan
Full Name of Fifth Assignor Naoyuki KOIZUMI	Assignor's Signature <i>Naoyuki KOIZUMI</i>	Date January 26, 2007
Address c/o Shinko Electric Industries Co., Ltd., 80, Oshimada-machi, Nagano-shi, Nagano, 381-2287, Japan		Citizenship Japan
Full Name of Sixth Assignor Kei MURAYAMA	Assignor's Signature <i>Kei Murayama</i>	Date January 26, 2007
Address c/o Shinko Electric Industries Co., Ltd., 80, Oshimada-machi, Nagano-shi, Nagano, 381-2287, Japan		Citizenship Japan
Full Name of Seventh Assignor Mitsutoshi HIGASHI	Assignor's Signature <i>Mitsutoshi Higashi</i>	Date January 26, 2007
Address c/o Shinko Electric Industries Co., Ltd., 80, Oshimada-machi, Nagano-shi, Nagano, 381-2287, Japan		Citizenship Japan
Full Name of Eighth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Ninth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Tenth Assignor	Assignor's Signature	Date
Address		Citizenship
Full Name of Eleventh Assignor	Assignor's Signature	Date
Address		Citizenship
Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		